



## Compact Packaging Scheme for Pressure Measurement Transducers

The developed pressure module packaging scheme (packaging) allows compact mounting of pressure measurement transducers, accommodating up to 512 pressure data channels. The packaging provides for removal of heat generated by the pressure measurement electronics using passive thermal conduction to the exterior surface. It allows for mounting of up to eight pneumatic connectors, for quick connection and disconnection of up to 512 pressure inputs.

### Practical/Commercial Applications:

Wind tunnel testing (wind engineering and aerodynamic fundamental and applied studies) and other applications involving pressure measurement of up to 512 data channels.

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### Patent Information

Provisional patent filed.

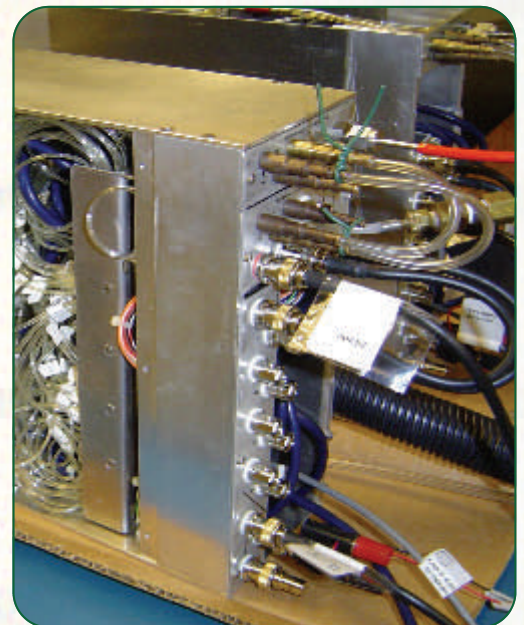
### Inventor Information

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### Features and Benefits

- Compact size allows for implementation in space-constrained testing environments.
- Innovative design offers extremely high channel density with >500 channels per module.
- Modularity bestows advantageous scalability and adaptability to the instrument.



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